



CUSTOMER ADVISORY ADV0217 UPDATE

FULL LASER MARKING INTRODUCTION

Change Description

This is an update to ADV0217. See the revision history table for information specific to this update.

In January 2003, Altera introduced a full topside laser mark on all Altera plastic body packages. Currently, the Altera device logo, part number, and date code are ink marked, while the Altera lot number and traceability code are laser marked.

Reason For Change

Laser marking provides manufacturing advantages to Altera by increasing mark permanency and quality, productivity gains through process simplification, and enables continuity of format. The use of a laser-marking process is also environmentally friendly when compared to current ink-marking processes.

Products Affected

The following plastic body packages will be affected: Plastic Lead Chip Carrier (PLCC), Quad Flat Package (QFP), Thin Quad Flat Package (TQFP), Plastic Ball Grid Array (PBGA), FineLine BGA (FBGA), Ultra FineLine Ball Grid Array (UFBGA), Plastic Dual in Line Package (PDIP), and Small Outline IC (SOIC) packages.

Product Traceability and Transition Dates

Altera plans to introduce the full laser marking towards the end of March 2008. After this date, customers may receive either laser marked or ink marked devices.

Contact

For more information, please contact your local Altera sales representative or Altera Customer Quality Engineering at customer-quality@altera.com.

In accordance with JESD46-C, this change is deemed acceptable to the customer if no acknowledgement is received within 30 days from this notification.

Revision History

Date	Rev	Description
11/11/2002	1.0.0	Initial Release
02/20/2008	1.1.0	Implementation on body sizes larger than 20X20 mm